Promex, Quik-Pak Showcase Expertise in Medtech Device Packaging & Assembly, Exhibit Air Cavity QFNs, Over Molded DFN / QFNs

Microelectronics Services Providers to Promote Capabilities Designed to Accelerate Time to Market at MEPTEC Medical Electronics Symposium in Portland, OR, September 14-15, 2016

Santa Clara, CA – June 30, 2016 – Promex and its Quik-Pak Division featured medtech/biotech device packaging and assembly solutions at 11 industry events in the first half of 2016:

- Last month, the companies exhibited at the IEEE Electronic Components and Technology Conference (ECTC) in Las Vegas, the International Microwave Symposium (IMS) in San Francisco, MEPTEC's MEMS Technology Symposium in San Jose and IMAPS New England 43rd Symposium & Expo on Advanced Packaging for Wireless Medical Devices in Boxborough, MA.
- In April, they exhibited at the IMAPS RF and Microwave Packaging (RAMP) workshop and tabletop exhibition in San Diego and the Metro IMAPS Vendor Day/Presentation in New York.
- In March, Promex and Quik-Pak were featured at a Biomedical Device Conference in San Jose, at GOMACTech in Orlando and at APEX Expo IPC 2016 in Las Vegas.
- The companies launched the year as Silver Sponsors of the International Microelectronics Assembly and Packaging Society (IMAPS) Advanced Packaging for Wireless Medical Devices Technical Workshop in San Diego, followed by MedTech World's Medical Device and Manufacturing (MD&M) West Expo in Anaheim.

At these events, Promex engaged attendees with its advanced engineering services, SMT assembly and high-reliability IC packaging from prototype to volume assembly. Quik-Pak, a division of Promex, attracted device manufacturers with its ability to provide a full suite of IC packaging options in three days or less. Together, the Promex and Quik-Pak facilities are ISO 13485:2003 and ISO 9001:2008 certified, ITAR registered and compliant to regulatory requirements for medical products.

Next up on the exhibit schedule is the Medical Electronics Symposium 2016, September 14-15, 2016 at Marylhurst University in Portland, OR. Hosted by SMTA, iNEMI and MEPTEC, this international conference focuses on advances in electronic technologies and advanced manufacturing, specifically targeting medical and bioscience applications.

About Promex

Promex specializes in engineering and proof of concept through production of Class III implantable and other complex medical devices. The company integrates conventional SMT with semiconductor microelectronic packaging and assembly, offering in-house wafer thinning, dicing, wirebond, flip chip and overmolding services – all of which are supported by an engineering team with more than 35 years of experience with complex assemblies. Promex operates a 30,000 square foot assembly facility in Silicon Valley with RoHS-optimized surface mount technology (SMT), Class 100 and 1000 clean rooms and fully controlled process flows for high reliability manufacturing. More information is available at www.promex-ind.com or by calling 408-496-0222.

About Quik-Pak

Quik-Pak's IC packaging solutions for complex RF/MW devices include air cavity plastic QFN packages, over-molded plastic QFN/DFN packages, custom transfer molded packaging, and custom assembly for ceramic, laminate, COF and COB. Quik-Pak also offers assembly services from prototype design validation to full production, as well as wafer preparation services including dicing, backgrinding and pick and place. The company's 15,000 square foot facility includes fully automated equipment for high throughput and maximum yield. More information about Promex's Quik-Pak Division is available at www.icproto.com or by calling 858-674-4676.

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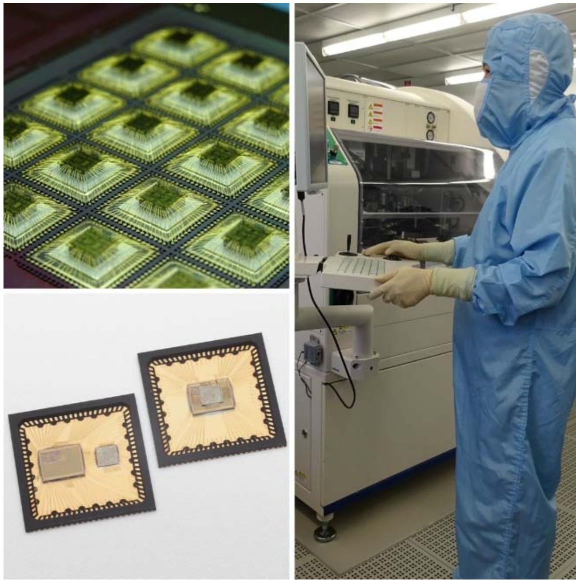

Photo caption:
Promex and its Quik-Pak Division exhibited medtech/biotech assembly and packaging solutions at 11 events in 2016. Featured services included mixed SMT component placement with integrated wirebond & flipchip and hermetic, COB & plastic assembly. The companies provide advanced engineering for concept to production manufacturing, Class 100/1000 clean rooms and fully controlled process flows for high reliability. Shown top left is a multi-die stack. Bottom left is an open-molded plastic package (OmPP) available in three days or fewer.